

<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25\text{ °C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1.0\text{ A}$ , $di_F/dt = 50\text{ A/}\mu\text{s}$ , $V_R = 30\text{ V}$	-	-	35	ns
		$T_J = 25\text{ °C}$	-	19	-	
		$T_J = 125\text{ °C}$	-	26	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ °C}$	-	3.1	-	A
		$T_J = 125\text{ °C}$	-	4.6	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ °C}$	-	30	-	nC
		$T_J = 125\text{ °C}$	-	60	-	

<b>THERMAL - MECHANICAL SPECIFICATIONS</b>					
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J, T_{Stg}$	- 65	-	175	°C
Thermal resistance, junction to case per leg	$R_{thJC}$	-	-	5	°C/W
Thermal resistance, junction to ambient per leg	$R_{thJA}$	-	-	80	
Thermal resistance, case to heatsink	$R_{thCS}$	-	-	-	
Weight		-	0.3	-	g
		-	0.01	-	oz.
Mounting torque		6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style D-PAK		6CWH02FN	

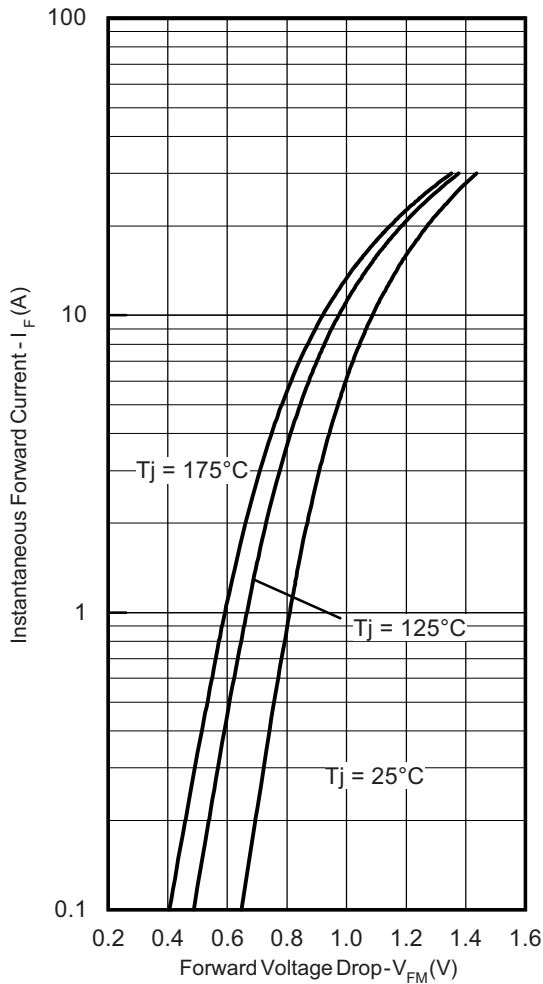


Fig. 1 - Maximum Forward Voltage Drop Characteristics

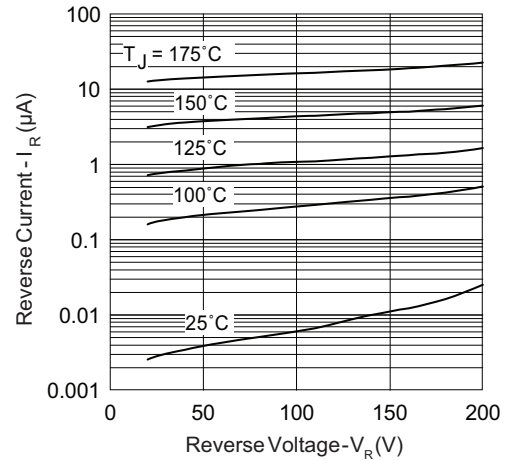


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

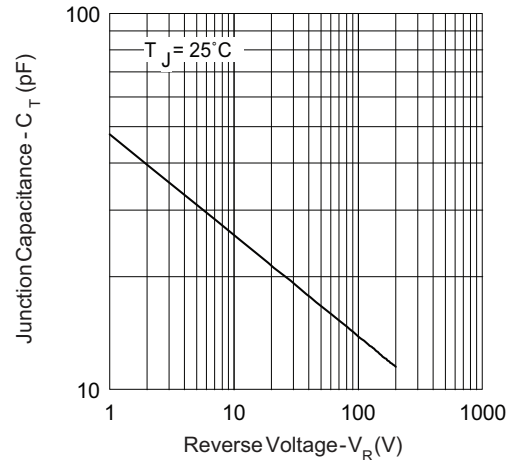
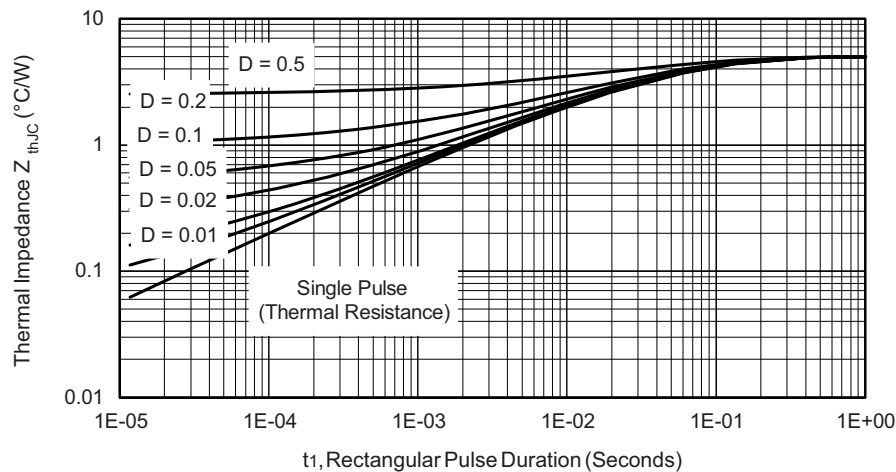


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage


 Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

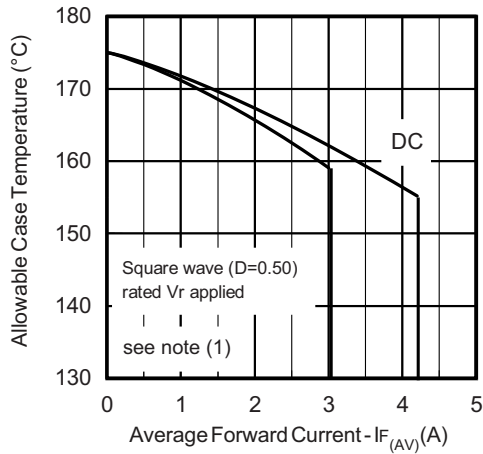


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

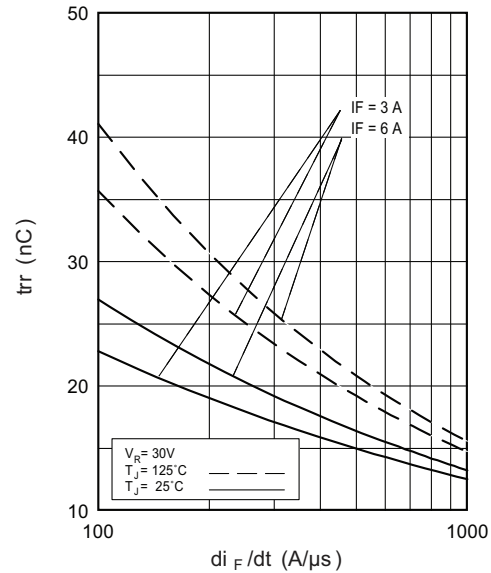


Fig. 7 - Typical Reverse Recovery vs.  $dI_F/dt$

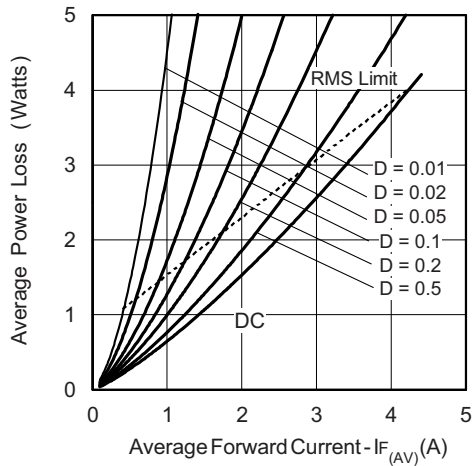


Fig. 6 - Forward Power Loss Characteristics

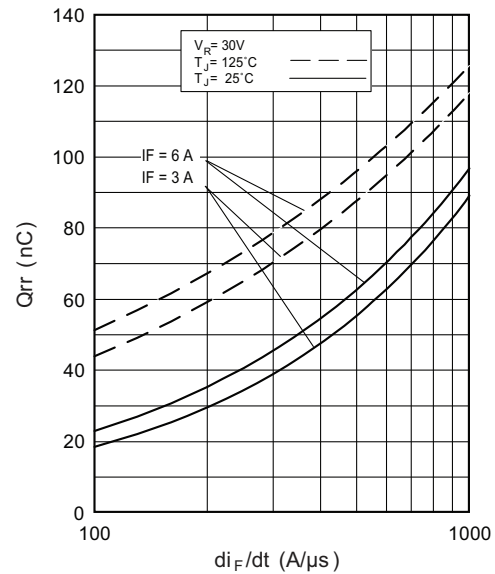


Fig. 8 - Typical Stored Charge vs.  $dI_F/dt$

### Note

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;  
 $P_d$  = Forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);  
 $P_{dREV}$  = Inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = Rated  $V_R$

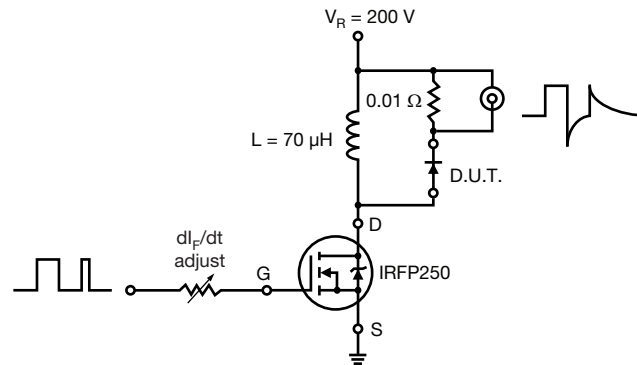


Fig. 9 - Reverse Recovery Parameter Test Circuit

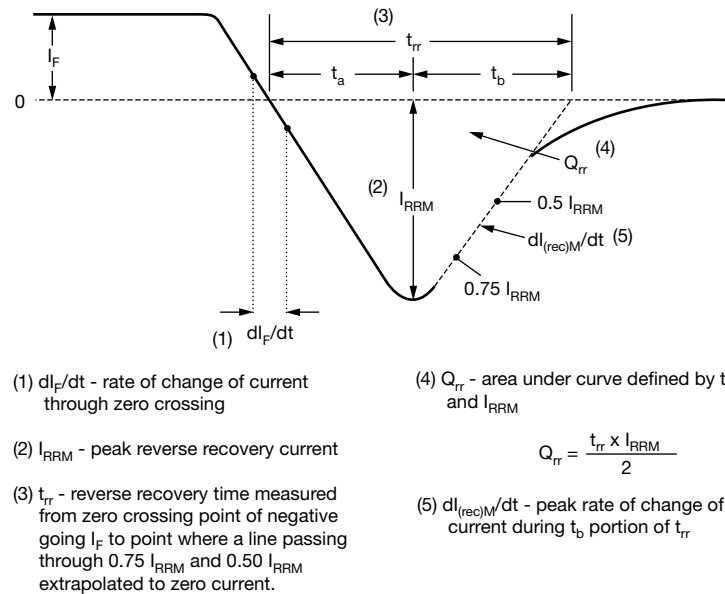


Fig. 10 - Reverse Recovery Waveform and Definitions

## ORDERING INFORMATION TABLE

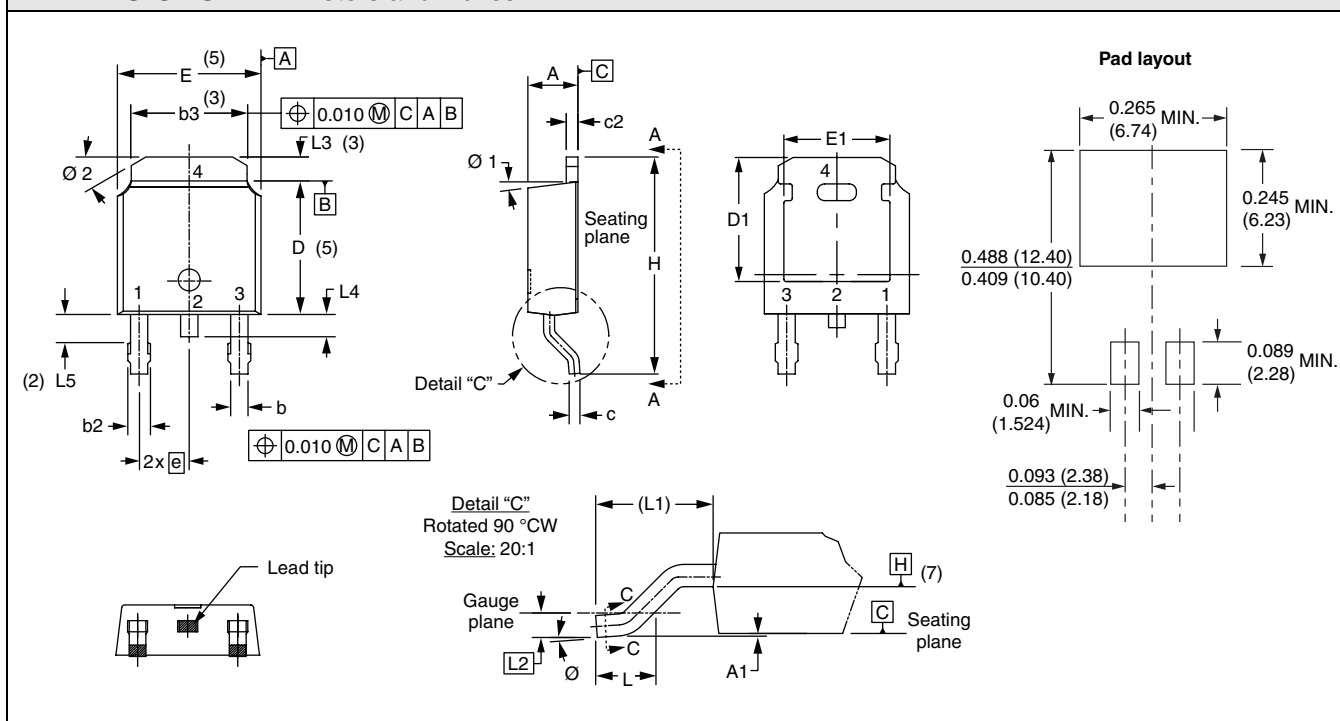
Device code	VS-	6	C	W	H	02	FN	TRL	PbF
	1	2	3	4	5	6	7	8	9

- 1** - Vishay Semiconductors product
- 2** - Current rating (6 = 6 A)
- 3** - Center tap configuration
- 4** - Package identifier:  
W = D-PAK
- 5** - H = Hyperfast recovery
- 6** - Voltage rating (02 = 200 V)
- 7** - FN = TO-252AA
- 8** -
  - None = Tube (50 pieces)
  - TR = Tape and reel
  - TRL = Tape and reel (left oriented)
  - TRR = Tape and reel (right oriented)
- 9** - PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95016">www.vishay.com/doc?95016</a>
Part marking information	<a href="http://www.vishay.com/doc?95059">www.vishay.com/doc?95059</a>
Packaging information	<a href="http://www.vishay.com/doc?95033">www.vishay.com/doc?95033</a>

## D-PAK (TO-252AA)

### DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
c	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	5.21	-	0.205	-	3
E	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
e	2.29 BSC		0.090 BSC		
H	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108 REF.		
L2	0.51 BSC		0.020 BSC		
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
Ø	0°	10°	0°	10°	
Ø1	0°	15°	0°	15°	
Ø2	25°	35°	25°	35°	

#### Notes

- Dimensioning and tolerancing as per ASME Y14.5M-1994
- Lead dimension uncontrolled in L5
- Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- Dimension b1 and c1 applied to base metal only
- Datum A and B to be determined at datum plane H
- Outline conforms to JEDEC outline TO-252AA



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